$I_{FAV} = 2x \cdot 10 A$ 

 $V_{RRM} =$ 

1200 V

200 ns

Backside: cathode

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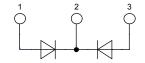
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# **Sonic Fast Recovery Diode**

High Performance Fast Recovery Diode Low Loss and Soft Recovery Common Cathode

Part number

DHG 20 C 1200 PB



Package:

- Housing: TO-220
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

### Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

# Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- · Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
  - Power dissipation within the diode
- Turn-on loss in the commutating switch

### Ratings

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V <sub>RRM</sub>	max. repetitive reverse voltage		T <sub>VJ</sub> = 25°C			1200	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 1200 V	$T_{VJ} = 25^{\circ}C$			10	μΑ
		$V_{R} = 1200 V$	$T_{VJ} = 125$ °C			0.2	mΑ
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 10 A	T <sub>VJ</sub> = 25°C			2.22	V
		$I_F = 20 A$				2.93	V
		I <sub>F</sub> = 10 A	T <sub>VJ</sub> = 125°C			2.23	V
		$I_F = 20 A$				3.14	V
I <sub>FAV</sub>	average forward current	rectangular d = 0.5	$T_c = 105$ °C			10	Α
V <sub>F0</sub>	threshold voltage slope resistance for power loss calculation only					1.23	V
r <sub>F</sub>						90	mΩ
R <sub>thJC</sub>	thermal resistance junction to case					1.50	K/W
T <sub>VJ</sub>	virtual junction temperature			-55		150	°C
P <sub>tot</sub>	total power dissipation		$T_C = 25^{\circ}C$			85	W
I <sub>FSM</sub>	max. forward surge current	t = 10 ms (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			60	Α
I <sub>RM</sub>	max. reverse recovery current		T <sub>VJ</sub> = 25°C		9		Α
		$I_F = 10 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 125^{\circ}C$		10.5		Α
t <sub>rr</sub>	reverse recovery time	$-di_F/dt = 250 A/\mu s$	$T_{VJ} = 25^{\circ}C$		200		ns
			$T_{VJ} = 125^{\circ}C$		350		ns
CJ	junction capacitance	$V_{R} = 600  V; f = 1  MHz$	T <sub>VJ</sub> = 25°C		4		pF



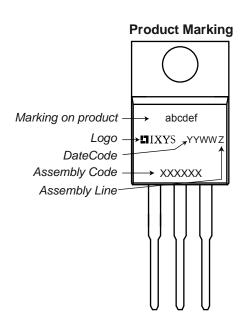
# DHG 20 C 1200 PB

Ratings

preliminary

				ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
I <sub>RMS</sub>	RMS current	per terminal 1)			35	Α	
R thCH	thermal resistance case to heatsink			0.50		K/W	
T <sub>stg</sub>	storage temperature		-55		150	°C	
Weight				2		g	
M <sub>D</sub>	mounting torque		0.4		0.6	Nm	
F <sub>c</sub>	mounting force with clip		20		60	Ν	

 $<sup>^{1)}</sup>$  I<sub>RMS</sub> is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a common cathode/anode configuration with a non-isolated backside, the current capability can be increased by connecting the backside.



### Part number

D = Diode

H = Sonic Fast Recovery Diode

G = extreme fast

20 = Current Rating [A]

C = Common Cathode

1200 = Reverse Voltage [V]

PB = TO-220AB (3)

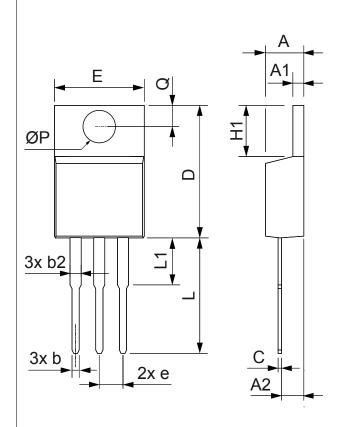
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DHG 20 C 1200 PB	DHG20C1200PB	Tube	50	505280



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### Outlines TO-220



Dim.	Millimeter		Inches		
	Min.	Max.	Min.	Max.	
Α	4.32	4.82	0.170	0.190	
A1	1.14	1.39	0.045	0.055	
A2	2.29	2.79	0.090	0.110	
b	0.64	1.01	0.025	0.040	
b2	1.15	1.65	0.045	0.065	
С	0.35	0.56	0.014	0.022	
D	14.73	16.00	0.580	0.630	
E	9.91	10.66	0.390	0.420	
е	2.54	BSC	0.100	BSC	
H1	5.85	6.85	0.230	0.270	
L	12.70	13.97	0.500	0.550	
L1	2.79	5.84	0.110	0.230	
ØP	3.54	4.08	0.139	0.161	
Q	2.54	3.18	0.100	0.125	

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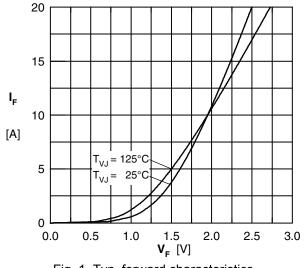


Fig. 1 Typ. forward characteristics

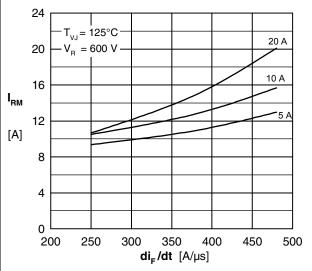


Fig. 3 Typical peak reverse current  $I_{RR}$  versus  $di_F/dt$  (125°C)

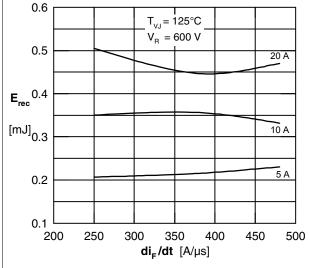


Fig. 5 Typ. recovery energy  $E_{rec}$  vs.  $di_F/dt$  (125°C)

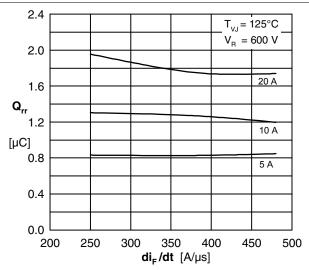


Fig. 2 Typical reverse recovery charge  $Q_{rr}$  versus.  $di_{F}/dt$  (125°C)

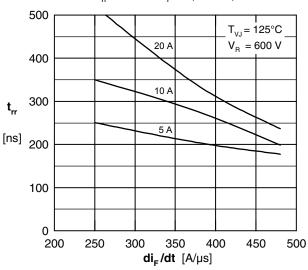


Fig. 4 Typ. recovery time t<sub>rr</sub> vs. di/dt (125°C)

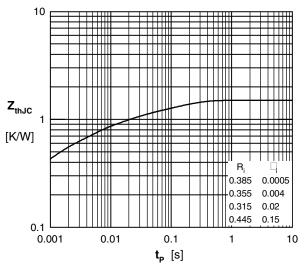


Fig. 6 Typ. transient thermal impedance

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